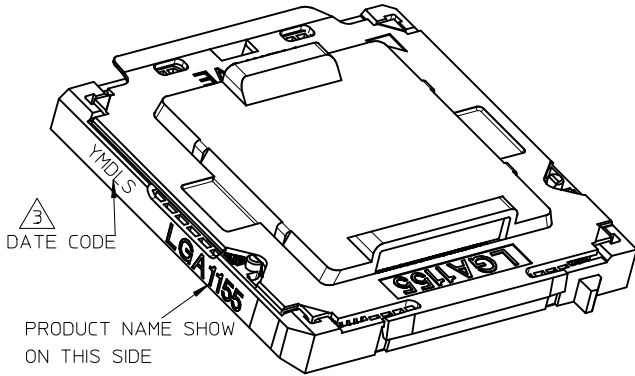
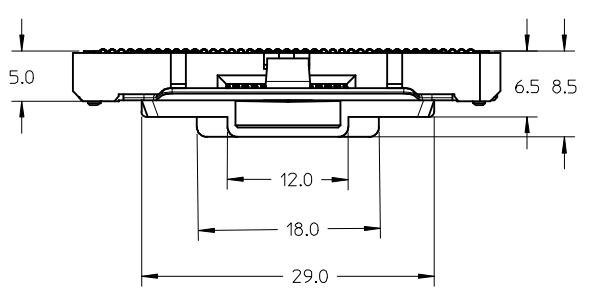
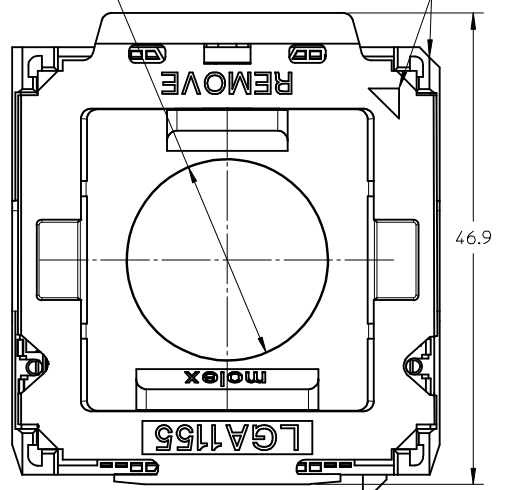


10 9 8 7 6 5 4 3 2 1

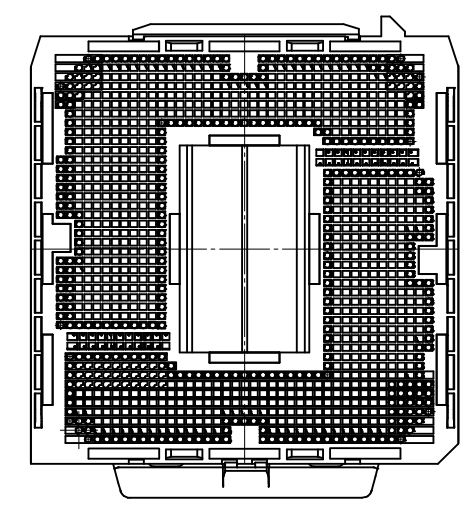
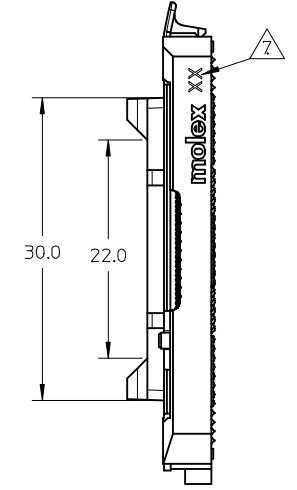


- NOTES:
- MATERIAL:
HOUSING AND CAP: HIGH TEMPERATURE THERMOPLASTIC, UL94V-0
CONTACT: HIGH STRENGTH COPPER ALLOY
SOLDER BALL: LEAD FREE SnAg3.0Cu0.5
 - PLATING:
50u" MIN. NICKEL AT PADDLE AND CONTACT AREA.
GOLD PLATING THICKNESS AT CONTACT AREA REFER TO TABLE.
 - DATE CODE "YMDLS" IS DEFINED AS:
"YEAR/MONTH/DAY/**".("***" IS MOLEX INTERNAL CONTROLLED).
 - 47596**** COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV DIRECTIVE 2000/53/EC.
 - PRODUCT SPECIFICATION PS-47596-001 APPLIES.
 - PACKAGE DRAWING PK-47596-001 APPLIES.
 - "XX" IS FOR CAVITY # (MOLEX INTERNAL USE)

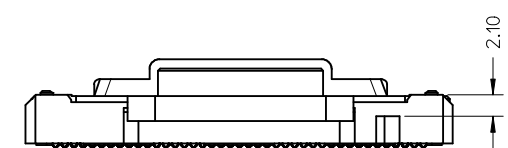
Ø 20
PICK AND PLACE
IN THIS ZONE



TOP VIEW



BOTTOM VIEW



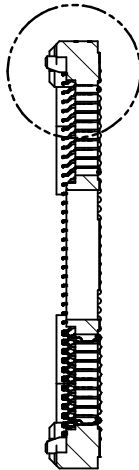
ENTER DESCRIPTION EC NO: SH2013-0312 DRWN: YXZHENG 2013/03/28 CHKD: APPR: AY IN 2013/04/16	QUALITY SYMBOLS $F_A=0$ $F_G=0$ $F_P=0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION		
				IN/MM	2:1	INCH			
				mm	INCH	DRAWN BY VLV DATE 2008/12/11		TITLE LGA1155 SOCKET	
				4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	CHECKED BY JKACH LIC DATE 2008/12/11		APPROVED BY DATE	
		2 PLACES ± 0.25 ± ---		1 PLACE ± 0.25 ± ---		ANGULAR ± 1 °			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO.	DOCUMENT NO.	SHEET NO.			
				SEE TABLE	SD-47596-200	1 OF 3			
				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

9 8 7 6 5 4 3 2 1

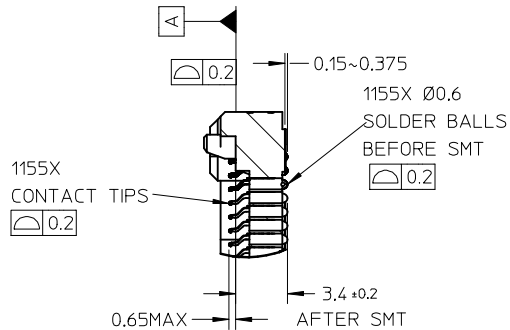
1155x CONTACT POINTS
FOR PACKAGE LANDS

$\varnothing 0.25$ A|B|C

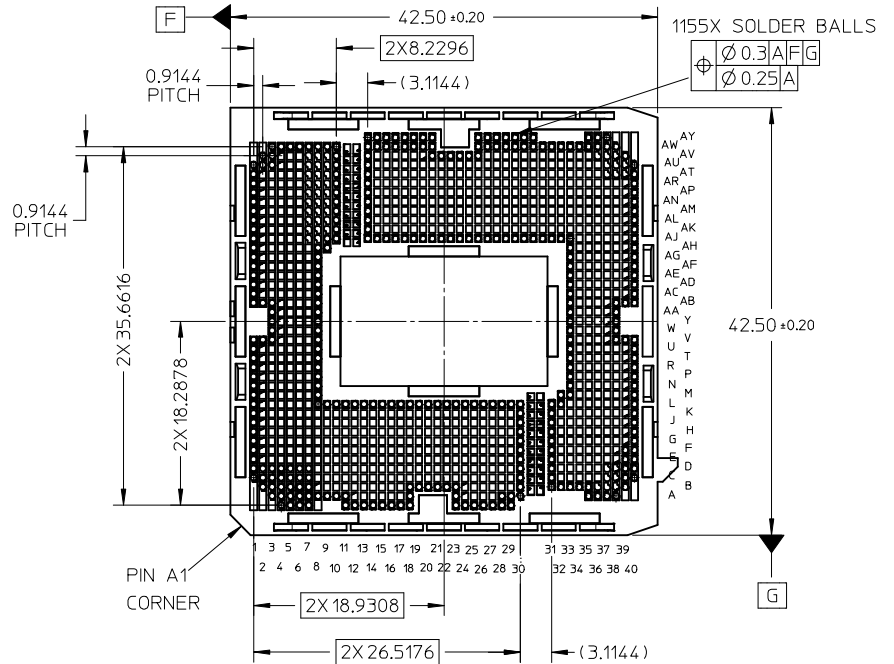
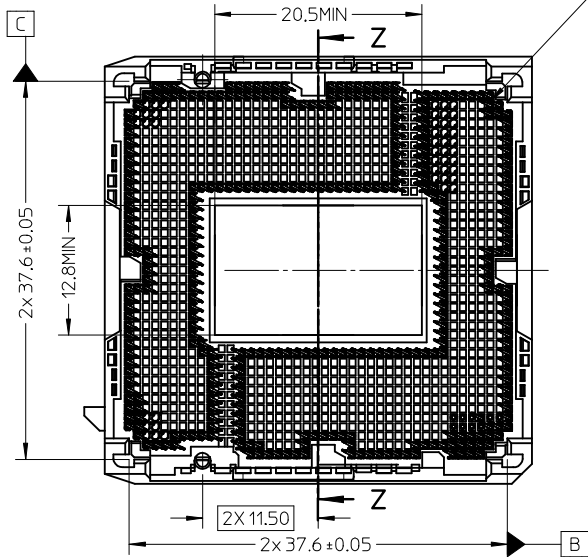
DETAIL1



SECTION Z-Z

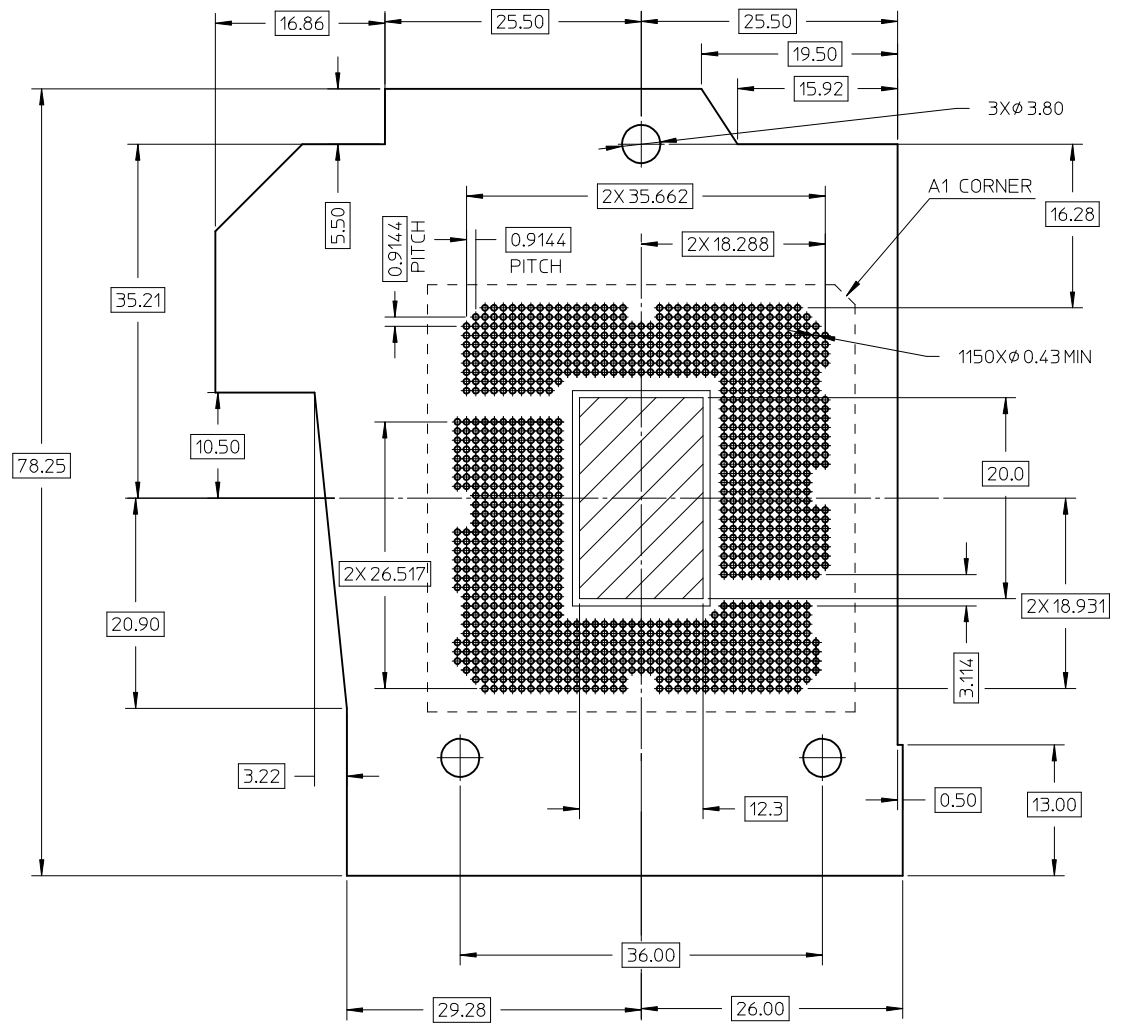


DETAIL1



PART NUMBER	PLATING THICKNESS ON CONTACT AREA
475960232	15u*(0.38um)MIN. GOLD
475960233	30u*(0.76um)MIN. GOLD

ENTER DESCRIPTION EC NO: SH2013-0312 DRWN: YXZHENG CHKD: APPR: AYIN	REVISION REV	QUALITY SYMBOLS F _A =0 F _B =0 F _C =0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION		
			mm	INCH	IN/MM	2:1	INCH			
DESCRIPTION 2013/03/28 2013/04/16	REV	QUALITY SYMBOLS	4 PLACES	± ---	± ---	DRAWN BY	DATE	TITLE LGA1155 SOCKET		
			3 PLACES	± ---	± ---	VLV	2008/12/11			
			2 PLACES	± 0.25	± ---	CHECKED BY	DATE			
			1 PLACE	± 0.25	± ---	JKACHLIC	2008/12/11			
			ANGULAR ± 1 °		APPROVED BY	DATE	MOLEX INCORPORATED			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SEE TABLE		MATERIAL NO.	DATE				
					SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				



PCB TOP SIDE KEEP OUT ZONE LAYOUT FOR REFERENCE

ENTER DESCRIPTION EC NO: SH2013-0312 DRWN: YXZHENG 2013/03/28 CHKD: CHKD: APPR: AYIN 2013/04/16 REV	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	$F_A = 0$ $F_C = 0$ $F_P = 0$	mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.25 ± --- 1 PLACE ± 0.25 ± --- ANGULAR ± 1 °	IN/MM	2:1	INCH	
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAWN BY: VLV DATE: 2008/12/11 CHECKED BY: JKACHLIC DATE: 2008/12/11 APPROVED BY: DATE:	TITLE: LGA1155 SOCKET		
			MATERIAL NO. DOCUMENT NO. SHEET NO. SEE TABLE SD-47596-200 3 OF 3	MOLEX INCORPORATED THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		